

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 61226933
PUBLICATION DATE : 08-10-86

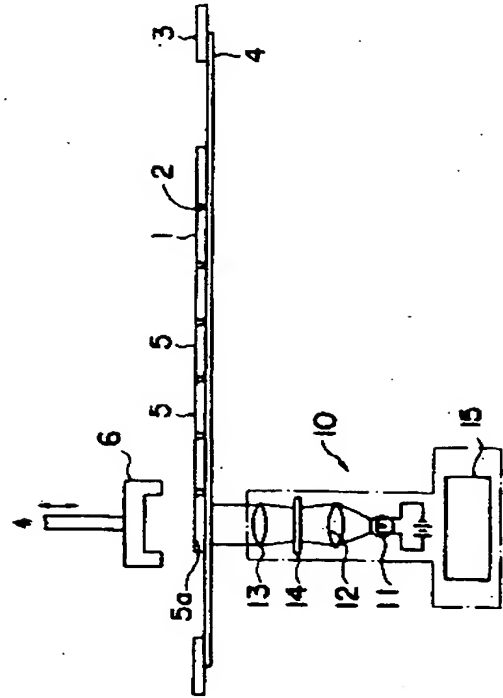
APPLICATION DATE : 30-03-85
APPLICATION NUMBER : 60067819

APPLICANT : TOSHIBA CORP;

INVENTOR : NODA YASUMASA;

INT.CL. : H01L 21/58

TITLE : MOUNTING APPARATUS



ABSTRACT : PURPOSE: To enable the application of the same mount tape to every size of semiconductor chips by a construction wherein a light source unit applying ultraviolet rays to each separate semiconductor chip from below the mount tape is disposed in a take-out stage.

CONSTITUTION: A mount tape 4 is stretched on a flat ring 3, and a semiconductor wafer 1 is put on the mount tape 4 and fixed thereon by the adhesion thereof. Then, a light source unit 10 is moved in the three-dimensional direction relatively to the semiconductor wafer 1 and set below a semiconductor chip 5a to be taken out, and applies ultraviolet rays to the mount tape under said semiconductor chip 5a. By this application, an adhesive in the irradiated part of the mount tape is set and consequently the adhesion thereof is reduced. Thus, an adsorption head 6 of a vacuum tweezers or the like or a take-out device such as a collet is lowered to hold the chip 5a, and thereby the chip 5a is taken out.

COPYRIGHT: (C)1986,JPO&Japio